



2048K x 32 Static RAM CMOS, High Speed Module

Features

- 2048K x 32 bit CMOS Static
- Random Access Memory
 - Access Times: 20, 25, and 35ns
 - Individual Byte Selects
 - Fully Static, No Clocks
 - TTL Compatible I/O
- High Density Package
 - 72 lead SIMM
 - Common Data Inputs and Outputs
- Single +3.3V ($\pm 10\%$) Supply Operation

DESCRIPTION

The EDI8G322048V is a high speed 64 megabit Static RAM module organized as 2048K words by 32 bits. This module is constructed from sixteen 1024K x 4 Static RAMs in SOJ packages on an epoxy laminate (FR4) board.

Four chip enables ($\overline{E_0}$ - $\overline{E_3}$) and the highest order address line are used to independently enable the four bytes as well as the low or high block of addressable memory space. Reading or writing can be executed on individual bytes or any combination of multiple bytes through proper use of selects.

The EDI8G322048V is offered in a 72 lead SIMM package, which enables 64 megabits of memory to be placed in less than 1.3 square inches of board space.

All inputs and outputs are TTL compatible and operate from a single 3.3V supply. Fully asynchronous circuitry requires no clocks or refreshing for operation and provides equal access and cycle times for ease of use.

*Pins PD1- PD4, are used to identify module memory density in applications where alternate modules can be interchanged.

PIN CONFIGURATION

NC	1	E4	37
NC	2	E3	38
PD3	3	A17	39
PD4	4	A16	40
VSS	5	G	41
PD1	6	VSS	42
PD2	7	DQ24	43
DQ0	8	DQ16	44
DQ8	9	DQ25	45
DQ1	10	DQ17	46
DQ9	11	DQ26	47
DQ2	12	DQ18	48
DQ10	13	DQ27	49
DQ3	14	DQ19	50
DQ11	15	A3	51
VCC	16	A10	52
A0	17	A4	53
A7	18	A11	54
A1	19	A5	55
A8	20	A12	56
A2	21	VCC	57
A9	22	A13	58
DQ12	23	A6	59
DQ4	24	DQ20	60
DQ13	25	DQ28	61
DQ5	26	DQ21	62
DQ14	27	DQ29	63
DQ6	28	DQ22	64
DQ15	29	DQ30	65
DQ7	30	DQ23	66
VSS	31	DQ31	67
W	32	VSS	68
A15	33	A18	69
A14	34	A19	70
E2	35	A20	71
E1	36	NC	72

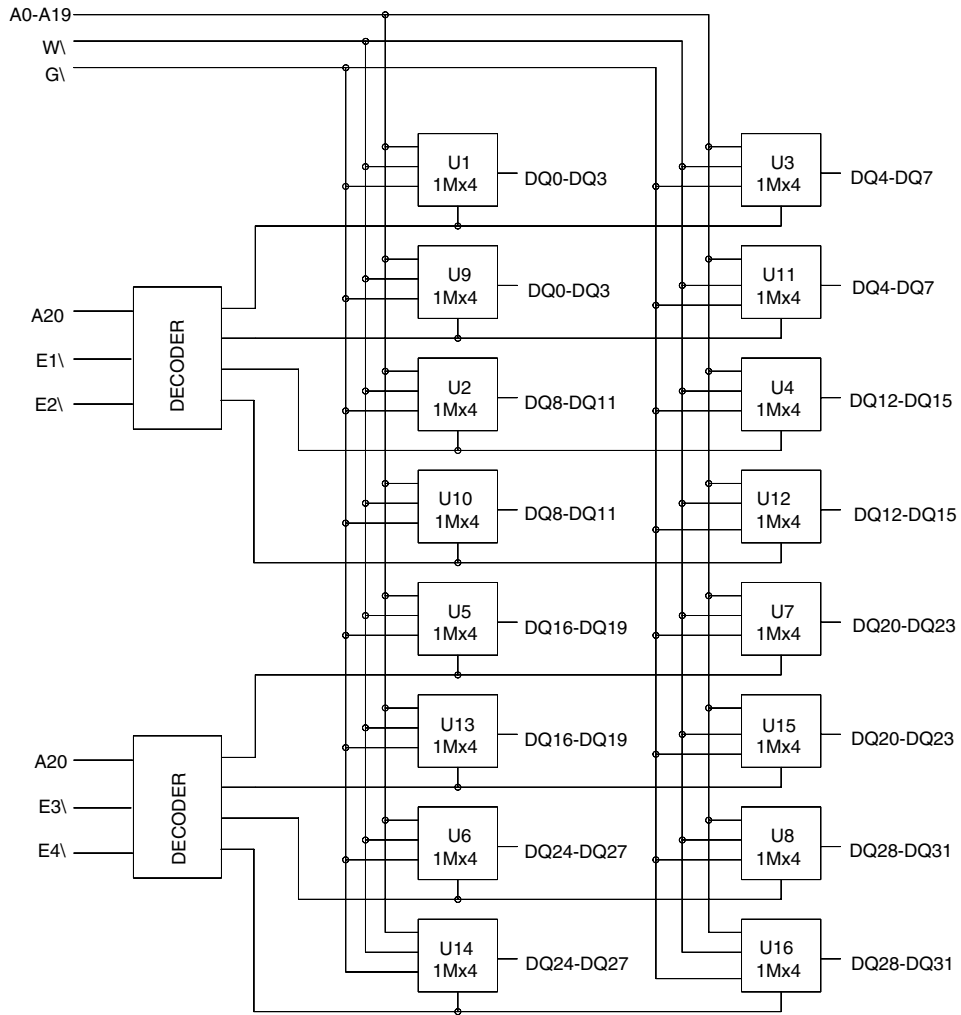
PIN NAMES

A ₀ -A ₂₀	Address Inputs
$\overline{E_1}$ - $\overline{E_4}$	Chip Enables
$\overline{W}$	Write Enable
$\overline{G}$	Output Enable
DQ ₀ -DQ ₃₁	Common Data Input/Output
VCC	Power (+3.3V $\pm 10\%$)
VSS	Ground
NC	No Connection

PD ₁	PD ₂	PD ₃	PD ₄
Open	VSS	VSS	Open



BLOCK DIAGRAM



8G322048C



ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to V _{SS}	-0.5V to 4.6V
Operating Temperature T _A (Ambient)	0°C to +70°C
Commercial	0°C to +125°C
Storage Temperature, Plastic	-55°C to +125°C
Power Dissipation	7.0 Watts
Output Current	20 mA

*Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

Parameter	Sym	Min	Typ	Max	Units
Supply Voltage	V _{CC}	3.0	3.3	3.6	V
Supply Voltage	V _{SS}	0	0	0	V
Input High Voltage	V _{IH}	2.2	—	V _{CC} +0.3	V
Input Low Voltage	V _{IL}	-0.3	—	0.8	V

AC TEST CONDITIONS

Input Pulse Levels	V _{SS} to 3.0V
Input Rise and Fall Times	3ns
Input and Output Timing Levels	1.5V
Output Load	1TTL, C _L = 30pF

(NOTE: For t_{BH}QZ, t_{BH}QZ and t_{WL}QZ, C_L = 5pF)

DC ELECTRICAL CHARACTERISTICS

Parameter	Sym	Conditions	Min	Typ	Max	Units
Operating Power Supply Current	I _{CC1}	W, $\overline{E} = \overline{V}_{IL}$, I _{I/O} = 0mA, Min Cycle			1750	mA
Standby (TTL) Power Supply Current	I _{CC2}	E ≥ V _{IH} , V _{IN} ≤ V _{IL} or V _{IN} ≥ V _{IH}			800	mA
Full Standby Power Supply Current	I _{CC3}	E ≥ V _{CC} - 0.2V			160	mA
CMOS		V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V				
Input Leakage Current	I _I	V _{IN} = 0V to V _{CC}	—	—	±80	μA
Output Leakage Current	I _O	V _{I/O} = 0V to V _{CC}	—	—	±20	μA
Output High Voltage	V _{OH}	I _{OH} = -4.0mA	2.4	—	—	V
Output Low Voltage	V _{OL}	I _{OL} = 8.0mA	—	—	0.4	V

*Typical: T_A = 25°C, V_{CC} = 3.3V

TRUTH TABLE

$\overline{E}1$	$\overline{E}2$	$\overline{E}3$	$\overline{E}4$	$\overline{W}$	$\overline{G}$	Operational Comments
H	H	H	H	H	H	Disabled
L	L	L	L	H	L	Read Double Word
L	L	L	L	L	H	Write Double Word
*	*	*	*	L	H	Write One or More Bytes in Double Word
*	*	*	*	H	L	Read One or More Bytes in Double Word

*Each enable controls one byte (x8) within the x32 (doubleword) and one or more byte enables may be driven valid during this operation.

CAPACITANCE

(f = 1.0MHz, V_{IN} = V_{CC} OR V_{SS})

Parameter	Sym	Max	Unit
Address Lines	C _I	120	pF
Data Lines	C _{D/Q}	20	pF
Chip Enable Line	C _C	120	pF
Write Line	C _N	120	pF

These parameters are sampled, not 100% tested.

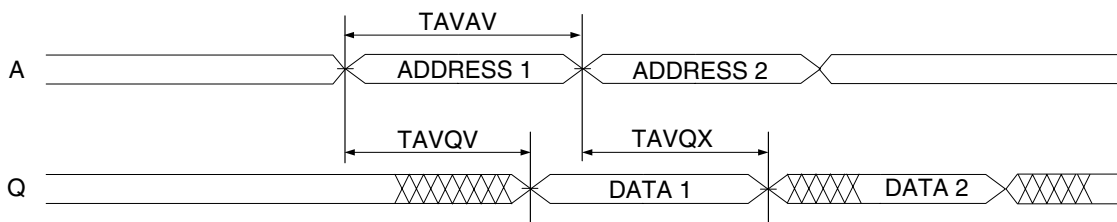


AC CHARACTERISTICS READ CYCLE

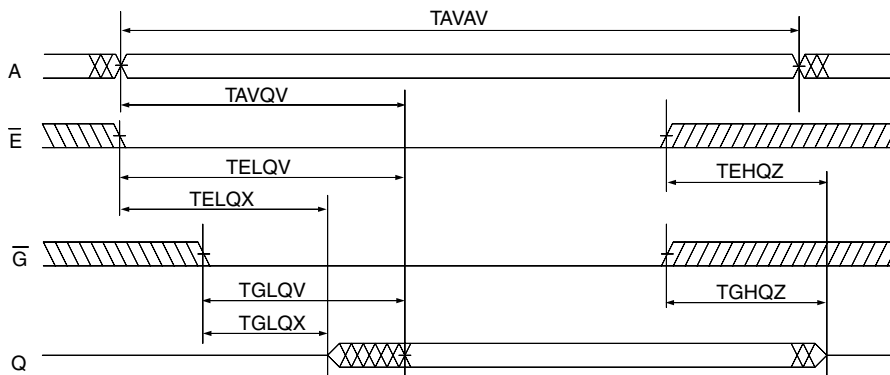
Parameter	Symbol		20ns		25ns		35ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	
Read Cycle Time	t _{AVA}	t _{RC}	20		25		35		ns
Address Access Time	t _{AVQV}	t _{AA}		20		25		35	ns
Chip Enable Access	t _{ELQV}	t _{ACS}		20		25		35	ns
Chip Enable to Output in Low Z ¹	t _{ELQX}	t _{CLZ}	3		3		3		ns
Chip Disable to Output in High Z ¹	t _{EHQZ}	t _{CHZ}		15		17		20	ns
Output Hold from Address Change	t _{AVQX}	t _{OH}	3		3		3		ns
Output Enable to Output Valid	t _{GLQV}	t _{OE}		15		17		20	ns
Output Enable to Output in Low Z ¹	t _{GLQX}	t _{OLZ}	0		0		0		ns
Output Disable to Output in High Z ¹	t _{GHQZ}	t _{OHZ}		15		17		20	ns

Note 1: Parameter guaranteed, but not tested.

Read Cycle 1 - $\overline{W}$ High, $\overline{G}$, $\overline{E}$ Low



Read Cycle 2 - $\overline{W}$ High



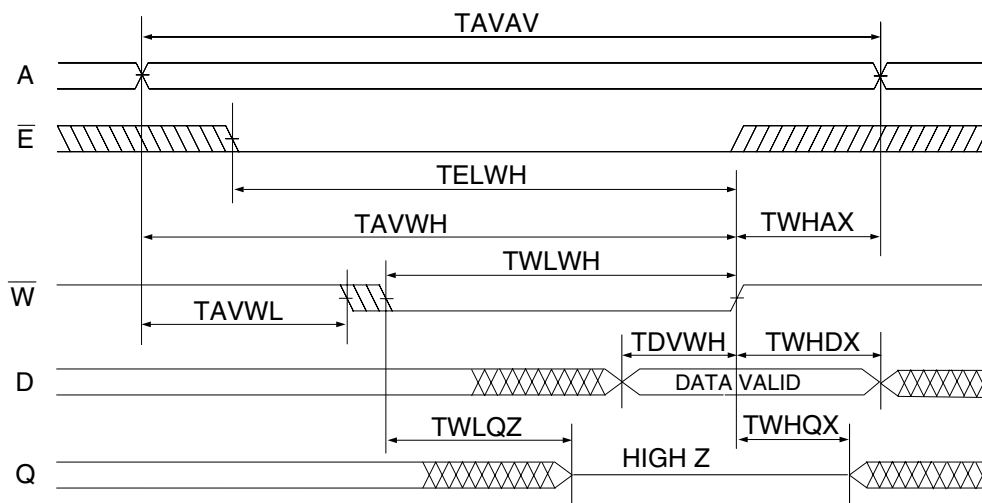


AC CHARACTERISTICS WRITE CYCLE

Parameter	Symbol		20ns		25ns		35ns		Units
	JEDEC	Alt.	Min	Max	Min	Max	Min	Max	
Write Cycle Time	tAVAV	tWC	20		25		35		ns
Chip Enable to End of Write	tELWH	tCW	15		20		25		ns
	tWLEH	tCW	15		20		25		ns
Address Setup Time	tAVWL	tAS	0		0		0		ns
	tAVEL	tAS	0		0		0		ns
Address Valid to End of Write	tAVWH	tAW	15		20		25		ns
	tAVEH	tAW	15		20		25		ns
Write Pulse Width	tWLWH	tWP	15		20		25		ns
	tLEH	tWP	15		20		25		ns
Write Recovery Time	tWHAX	tWR	0		0		0		ns
	tEHAX	tWR	0		0		0		ns
Data Hold Time	tWHDX	tDH	3		0		0		ns
	tEHDX	tDH	3		0		0		ns
Write to Output in High Z ¹	tWLQZ	tWHZ	0	8	0	12	0	15	ns
Data to Write Time	tdVWH	tdW	12		15		20		ns
	tdVEH	tdW	12		15		20		ns
Output Active from End of Write ¹	tWHQX	tWLZ	3		3		3		ns

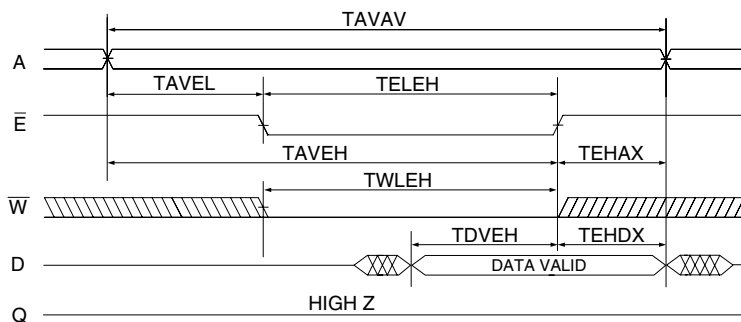
Note 1: Parameter guaranteed, but not tested.

Write Cycle 1 - $\overline{W}$ Controlled





Write Cycle 2 - $\bar{E}$ Controlled

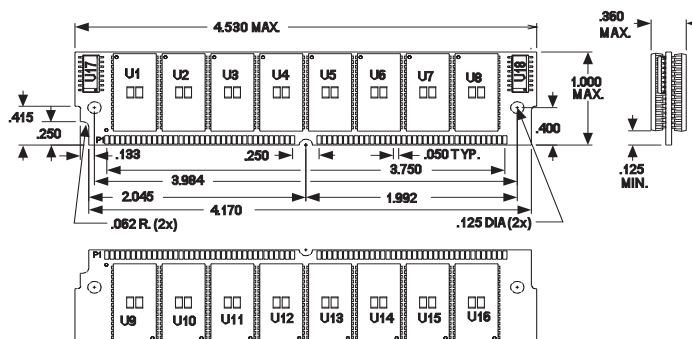


Ordering Information

Part Number	Speed (ns)
EDI8G322048V20MMC	20
EDI8G322048V25MMC	25
EDI8G322048V35MMC	35

Package Descriptions

72 LEAD SIMM



ALL DIMENSIONS ARE IN INCHES